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Global Molybdenum Copper Electronic Packaging Material Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global Molybdenum Copper Electronic Packaging Material market size was valued at US$ 959 million in 2025 and is forecast to a readjusted size of US$ 1391 million by 2032 with a CAGR of 5.5% during review period.

Molybdenum copper electronic packaging material is a functional composite material based on molybdenum (Mo) and copper (Cu) as basic elements. By adjusting the composition ratio and processing technology, it achieves adjustable coefficient of thermal expansion (CTE), high thermal conductivity, excellent mechanical strength and other characteristics. It is widely used in electronic packaging scenarios such as high-frequency communication and power devices. The core types of molybdenum copper electronic packaging materials are mainly divided into two categories based on structural and functional differences:

Layered composite type: a sandwich structure represented by copper molybdenum copper (Cu/Mo/Cu), with a middle layer of molybdenum or molybdenum copper alloy (thickness accounting for 30% -50%) and an outer layer of high-purity copper. Its thermal conductivity can reach 240-280 W/m · K, and its CTE can be adjusted to 6.5-8.5 ? 10 ??/K. It has excellent compatibility with silicon chips (4-7 ? 10 ??/K) and can effectively reduce the risk of interface failure caused by thermal stress.

Dispersion composite type: Molybdenum powder and copper powder are mixed and sintered using powder metallurgy technology to form a uniformly distributed biphasic structure. The material has a density of 9.5-10.2 g/cm ? and combines high tensile strength (? 400 MPa) and conductivity (? 45% IACS), making it suitable for packaging

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substrates in high vibration environments.

Outstanding thermal management efficiency: The thermal conductivity of molybdenum copper alloy (240-300 W/m · K) is significantly higher than that of traditional packaging materials (such as 170-200 W/m · K of aluminum silicon carbide), which can reduce the temperature rise of power devices by 15% -20% and extend their service life. High process adaptability: Foil or sheet materials with a thickness of 0.05-3 mm can be prepared through rolling composite technology, with a surface roughness (Ra) of ? 0.8 ? m. It supports precision processing such as laser cutting and chemical etching, and is suitable for high-density integrated circuit packaging requirements. Strong environmental reliability: Molybdenum has a melting point of 2620 ° C and can withstand working temperatures of 300-500 ° C for a long time in high-temperature packaging scenarios without oxidation or volatilization issues, ensuring the airtightness of the packaging.

The industrial production of molybdenum copper electronic packaging materials mainly relies on two types of technologies:

Rolling composite process: Molybdenum plate and copper foil are metallurgically bonded by hot rolling (temperature 800-950 ° C), with an interface shear strength of ? 80 MPa. The production efficiency is 30% -50% higher than powder metallurgy method, and it is suitable for continuous production of large-sized (? 600 mm wide) plates.

Copper infiltration sintering process: Using molybdenum powder as the matrix (particle size 1-5 ? m), after isostatic pressing, high-temperature copper infiltration (1350-1450 ° C) is carried out. The finished product has a density of ? 98% and a porosity of no more than 1%, which can prepare structural components with complex and irregular shapes.

Molybdenum copper electronic packaging materials have been widely applied in the following fields:

High frequency communication module: In 5G base station RF devices, its low CTE characteristics can reduce signal transmission delay by 10% -15%, and at the same time, through high thermal conductivity design, the junction temperature of the power amplifier chip is controlled within 85 ° C.

Power semiconductor packaging: used as an insulating substrate for IGBT modules, with a thermal resistance of ? 0.15 ° C · cm ?/W, supporting current density increase to over 200 A/cm ?, meeting the requirements of new energy vehicle electronic control

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systems.

Optoelectronic device heat dissipation: In laser diode packaging, the heat dissipation module containing molybdenum copper carrier can improve the stability of optical power output to ± 1.5%, which is suitable for data center optical communication equipment. In 2025, global Molybdenum Copper Electronic Packaging Material production reached approximately 6,800 MT, with an average global market price of around US$ 137 per kg.

The annual production capacity of molybdenum copper electronic packaging materials is 10,000 tons, with a gross profit margin of about 30%.

Upstream: Molybdenum powder; Electrolytic copper or high-purity copper; Powder metallurgy materials; High purity metal materials.

Downstream: high-frequency communication module, power semiconductor packaging, optoelectronic device heat dissipation.

The cost of raw materials is about 55%; The manufacturing and processing cost is about 25%; The cost of equipment and energy consumption is about 10%; The labor and management costs are about 5%; The cost of surface treatment and testing is about 5%.

This report is a detailed and comprehensive analysis for global Molybdenum Copper Electronic Packaging Material market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Molybdenum Copper Electronic Packaging Material market size and forecasts, in consumption value ($ Million), sales quantity (Tons), and average selling prices (US$/Ton), 2021-2032

Global Molybdenum Copper Electronic Packaging Material market size and forecasts by region and country, in consumption value ($ Million), sales quantity (Tons), and average

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selling prices (US$/Ton), 2021-2032

Global Molybdenum Copper Electronic Packaging Material market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (Tons), and average selling prices (US$/Ton), 2021-2032

Global Molybdenum Copper Electronic Packaging Material market shares of main players, shipments in revenue ($ Million), sales quantity (Tons), and ASP (US$/Ton), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries
To assess the growth potential for Molybdenum Copper Electronic Packaging Material
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace
This report profiles key players in the global Molybdenum Copper Electronic Packaging Material market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include ALMT Corp, AMETEK, H.C. Starck Hermsdorf GmbH, Negele Hartmetall-Technik GmbH, Santier, ATT Advanced Elemental Materials, Changzhou Fuxi Technology, Changsha Saneway Electronic Materials, Luoyang Combat Tungsten & Molybdenum Materials, Shaanxi Puwei Electronic Technology, etc.
This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Molybdenum Copper Electronic Packaging Material market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Mo60Cu40

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Mo75Cu25

Mo80Cu20

Mo85Cu15

Other

Market segment by Structure

Layered Composite Type

Dispersed Composite Type

Market segment by Preparation Process

Rolling Composite Process?

Copper Infiltration Sintering Process?

Market segment by Application

High Frequency Communication Module

Power Semiconductor Packaging

Heat Dissipation Of Optoelectronic Devices

Other

Major players covered

ALMT Corp

AMETEK

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H.C. Starck Hermsdorf GmbH

Negele Hartmetall-Technik GmbH

Santier

ATT Advanced Elemental Materials

Changzhou Fuxi Technology

Changsha Saneway Electronic Materials

Luoyang Combat Tungsten & Molybdenum Materials

Shaanxi Puwei Electronic Technology

ATTL Advanced Materials

Starshining Advanced Materials

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)
South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Molybdenum Copper Electronic Packaging Material product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Molybdenum Copper Electronic Packaging Material, with price, sales quantity, revenue, and global market share of Molybdenum Copper Electronic Packaging Material from 2021 to 2026.

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Chapter 3, the Molybdenum Copper Electronic Packaging Material competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Molybdenum Copper Electronic Packaging Material breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026.and Molybdenum Copper Electronic Packaging Material market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Molybdenum Copper Electronic Packaging Material.

Chapter 14 and 15, to describe Molybdenum Copper Electronic Packaging Material sales channel, distributors, customers, research findings and conclusion.

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Contents

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2 MANUFACTURERS PROFILES

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3 COMPETITIVE ENVIRONMENT: MOLYBDENUM COPPER ELECTRONIC PACKAGING MATERIAL BY MANUFACTURER

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List Of Tables

LIST OF TABLES

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List Of Figures

LIST OF FIGURES

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